

Chipsmall Limited consists of a professional team with an average of over 10 year of expertise in the distribution of electronic components. Based in Hongkong, we have already established firm and mutual-benefit business relationships with customers from, Europe, America and south Asia, supplying obsolete and hard-to-find components to meet their specific needs.

With the principle of "Quality Parts, Customers Priority, Honest Operation, and Considerate Service", our business mainly focus on the distribution of electronic components. Line cards we deal with include Microchip, ALPS, ROHM, Xilinx, Pulse, ON, Everlight and Freescale. Main products comprise IC, Modules, Potentiometer, IC Socket, Relay, Connector. Our parts cover such applications as commercial, industrial, and automotives areas.

We are looking forward to setting up business relationship with you and hope to provide you with the best service and solution. Let us make a better world for our industry!



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Power MOSFET

60 V, 4.7 m Ω , 93 A, Single N-Channel

Features

- Small Footprint (5x6 mm) for Compact Design
- Low R_{DS(on)} to Minimize Conduction Losses
- Low Q_G and Capacitance to Minimize Driver Losses
- NVMFS5C646NLWF Wettable Flank Option for Enhanced Optical Inspection
- AEC-Q101 Qualified and PPAP Capable
- These Devices are Pb-Free, Halogen Free/BFR Free and are RoHS Compliant

MAXIMUM RATINGS (T, I = 25°C unless otherwise noted)

Parameter			Symbol	Value	Unit
Drain-to-Source Voltage			V_{DSS}	60	V
Gate-to-Source Voltage	Э		V_{GS}	±20	V
Continuous Drain	Steady	T _C = 25°C	I _D	93	Α
Current R _{θJC} (Notes 1, 3)		T _C = 100°C		65	
Power Dissipation	State	T _C = 25°C	P_{D}	79	W
R _{θJC} (Note 1)		T _C = 100°C		40	
Continuous Drain	Steady	T _A = 25°C	I _D	20	Α
Current R _{0JA} (Notes 1, 2, 3)		T _A = 100°C		14	
Power Dissipation	State	T _A = 25°C	P_{D}	3.7	W
R _{θJA} (Notes 1 & 2)		T _A = 100°C		1.8	
Pulsed Drain Current	T _A = 25	°C, t _p = 10 μs	I _{DM}	750	Α
Operating Junction and Storage Temperature			T _J , T _{stg}	-55 to +175	°C
Source Current (Body Diode)			I _S	100	Α
Single Pulse Drain-to-Source Avalanche Energy (I _{L(pk)} = 5 A)			E _{AS}	185	mJ
Lead Temperature for Soldering Purposes (1/8" from case for 10 s)			TL	260	°C

Stresses exceeding those listed in the Maximum Ratings table may damage the device. If any of these limits are exceeded, device functionality should not be assumed, damage may occur and reliability may be affected.

THERMAL RESISTANCE MAXIMUM RATINGS

Parameter	Symbol	Value	Unit
Junction-to-Case - Steady State	$R_{\theta JC}$	1.9	°C/W
Junction-to-Ambient - Steady State (Note 2)	$R_{\theta JA}$	41	

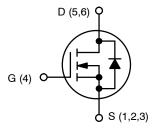
- 1. The entire application environment impacts the thermal resistance values shown, they are not constants and are only valid for the particular conditions noted.
- 2. Surface-mounted on FR4 board using a 650 mm², 2 oz. Cu pad.
- 3. Maximum current for pulses as long as 1 second is higher but is dependent on pulse duration and duty cycle.



ON Semiconductor®

www.onsemi.com

V _{(BR)DSS} R _{DS(ON)} MAX		I _D MAX
60 V	4.7 m Ω @ 10 V	93 A
	6.3 mΩ @ 4.5 V	93 A



N-CHANNEL MOSFET



STYLE 1

D S XXXXXX S **AYWZZ** S CASE 488AA

XXXXXX = 5C646L

(NVMFS5C646NL) or

MARKING DIAGRAM

D

D

646LWF

(NVMFS5C646NLWF)

= Assembly Location Α = Year W = Work Week ZZ = Lot Traceability

ORDERING INFORMATION

See detailed ordering, marking and shipping information in the package dimensions section on page 5 of this data sheet.

ELECTRICAL CHARACTERISTICS ($T_J = 25^{\circ}C$ unless otherwise specified)

Parameter	Symbol	Test Condition		Min	Тур	Max	Unit	
OFF CHARACTERISTICS							•	
Drain-to-Source Breakdown Voltage	V _{(BR)DSS}	$V_{GS} = 0 \text{ V}, I_D = 250 \mu\text{A}$		60			V	
Drain-to-Source Breakdown Voltage Temperature Coefficient	V _{(BR)DSS} /				15.5		mV/°C	
Zero Gate Voltage Drain Current	I _{DSS}	V _{GS} = 0 V, T _J = 25 °C				10		
		V _{DS} = 60 V	T _J = 125°C			250	μΑ	
Gate-to-Source Leakage Current	I _{GSS}	$V_{DS} = 0 \text{ V}, V_{GS} = \pm 16 \text{ V}$				±100	nA	
ON CHARACTERISTICS (Note 4)					-			
Gate Threshold Voltage	V _{GS(TH)}	$V_{GS} = V_{DS}, I_D$	= 250 μΑ	1.2		2.0	V	
Threshold Temperature Coefficient	V _{GS(TH)} /T _J				-4.9		mV/°C	
Drain-to-Source On Resistance	R _{DS(on)}	V _{GS} = 10 V	I _D = 50 A		3.8	4.7	_	
		V _{GS} = 4.5 V	I _D = 50 A		5.0	6.3	mΩ	
Forward Transconductance	9FS	V _{DS} = 15 V, I _E	_O = 50 A		105		S	
CHARGES, CAPACITANCES & GATE RE	SISTANCE				•	•	•	
Input Capacitance	C _{ISS}	V _{GS} = 0 V, f = 1 MHz, V _{DS} = 25 V			2164			
Output Capacitance	C _{OSS}				900		pF	
Reverse Transfer Capacitance	C _{RSS}				17			
Total Gate Charge	Q _{G(TOT)}	V _{GS} = 4.5 V, V _{DS} = 30 V; I _D = 25 A			15.7			
Total Gate Charge	Q _{G(TOT)}	V _{GS} = 10 V, V _{DS} = 30 V; I _D = 25 A			33.7		1	
Threshold Gate Charge	Q _{G(TH)}	V _{GS} = 4.5 V, V _{DS} = 30 V; I _D = 25 A			1.5		nC	
Gate-to-Source Charge	Q _{GS}				5.6			
Gate-to-Drain Charge	Q_{GD}				5.1			
Plateau Voltage	V _{GP}				2.8		V	
SWITCHING CHARACTERISTICS (Note 5)					•	•	
Turn-On Delay Time	t _{d(ON)}				10.4			
Rise Time	t _r	V _{GS} = 4.5 V, V _C	ns = 30 V,		14.9		ns ns	
Turn-Off Delay Time	t _{d(OFF)}	V_{GS} = 4.5 V, V_{D} I_{D} = 25 A, R_{G}	= 2.5 Ω		23.6			
Fall Time	t _f				5.1		1	
DRAIN-SOURCE DIODE CHARACTERIS	TICS					•	•	
Forward Diode Voltage	V _{SD}	V _{GS} = 0 V,	T _J = 25°C		0.88	1.2		
	I _S = 50		T _J = 125°C		0.78		V	
Reverse Recovery Time	t _{RR}	$V_{GS} = 0 \text{ V, dIS/dt} = 100 \text{ A/}\mu\text{s,}$ $I_{S} = 50 \text{ A}$			40.9			
Charge Time	ta				20.8		ns	
Discharge Time	t _b				20.1		1	
Reverse Recovery Charge	Q _{RR}				32		nC	

Product parametric performance is indicated in the Electrical Characteristics for the listed test conditions, unless otherwise noted. Product performance may not be indicated by the Electrical Characteristics if operated under different conditions.

^{4.} Pulse Test: pulse width \leq 300 μ s, duty cycle \leq 2%. 5. Switching characteristics are independent of operating junction temperatures.

TYPICAL CHARACTERISTICS

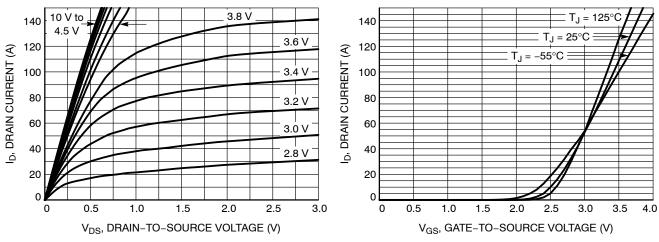


Figure 1. On-Region Characteristics

Figure 2. Transfer Characteristics

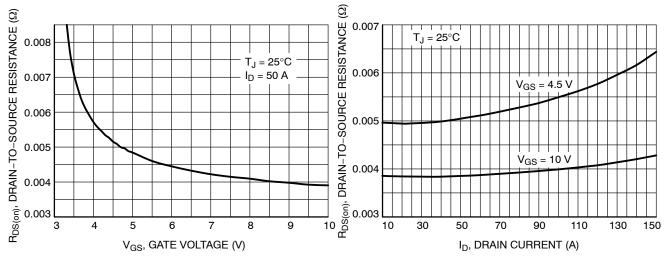


Figure 3. On-Resistance vs. Gate-to-Source Voltage

Figure 4. On-Resistance vs. Drain Current and Gate Voltage

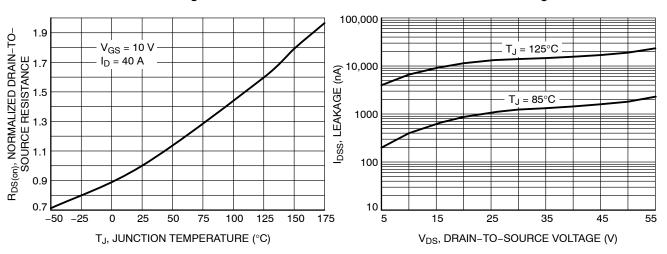
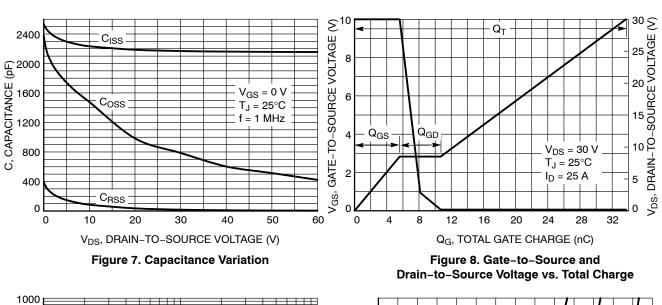


Figure 5. On–Resistance Variation with Temperature

Figure 6. Drain-to-Source Leakage Current vs. Voltage

TYPICAL CHARACTERISTICS



 $V_{GS} = 4.5 V$ V_{DD} = 30 V $I_D = 25 A$ 100 t, TIME (ns) $t_{d(on)}$ 10 10 100 R_G , GATE RESISTANCE (Ω)

Figure 9. Resistive Switching Time Variation vs. Gate Resistance

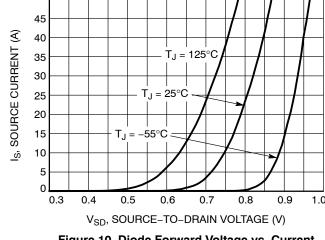


Figure 10. Diode Forward Voltage vs. Current

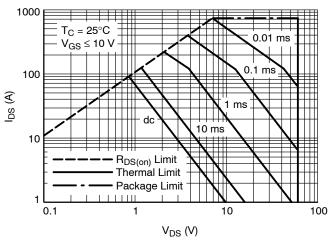


Figure 11. Safe Operating Area

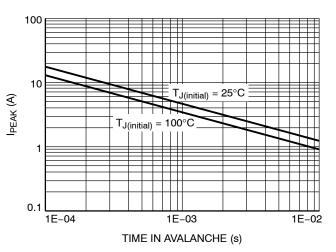


Figure 12. I_{PEAK} vs. Time in Avalanche

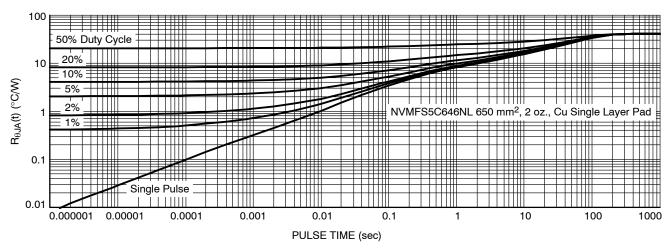


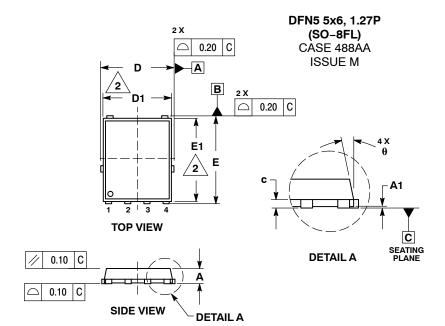
Figure 13. Thermal Characteristics

DEVICE ORDERING INFORMATION

Device	Marking	Package	Shipping [†]
NVMFS5C646NLT1G	5C646L	DFN5 (Pb-Free)	1500 / Tape & Reel
NVMFS5C646NLWFT1G	646LWF	DFN5 (Pb-Free, Wettable Flanks)	1500 / Tape & Reel
NVMFS5C646NLT3G	5C646L	DFN5 (Pb-Free)	5000 / Tape & Reel
NVMFS5C646NLWFT3G	646LWF	DFN5 (Pb-Free, Wettable Flanks)	5000 / Tape & Reel
NVMFS5C646NLAFT1G	5C646L	DFN5 (Pb-Free)	1500 / Tape & Reel
NVMFS5C646NLWFAFT1G	646LWF	DFN5 (Pb-Free, Wettable Flanks)	1500 / Tape & Reel

[†]For information on tape and reel specifications, including part orientation and tape sizes, please refer to our Tape and Reel Packaging Specifications Brochure, BRD8011/D.

PACKAGE DIMENSIONS



NOTES:

- DIMENSIONING AND TOLERANCING PER ASME Y14.5M, 1994.
- 2. CONTROLLING DIMENSION: MILLIMETER.
 3. DIMENSION D1 AND E1 DO NOT INCLUDE
- MOLD FLASH PROTRUSIONS OR GATE BURRS.

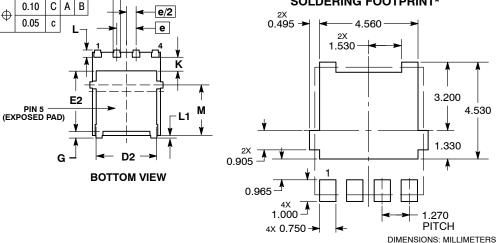
	MILLIMETERS			
DIM	MIN	NOM	MAX	
Α	0.90	1.00	1.10	
A1	0.00		0.05	
b	0.33	0.41	0.51	
С	0.23	0.28	0.33	
D	5.00	5.15	5.30	
D1	4.70	4.90	5.10	
D2	3.80	4.00	4.20	
E	6.00	6.15	6.30	
E1	5.70	5.90	6.10	
E2	3.45	3.65	3.85	
е	1.27 BSC			
G	0.51	0.575	0.71	
K	1.20	1.35	1.50	
L	0.51	0.575	0.71	
L1	0.125 REF			
М	3.00	3.40	3.80	
θ	0 °		12 °	

STYLE 1:

PIN 1. SOURCE

- SOURCE
- SOURCE GATE
- DRAIN





*For additional information on our Pb-Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

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